### SUBMINIATURE SOLID STATE LAMP

Part Number: AM27CGCK09 Green

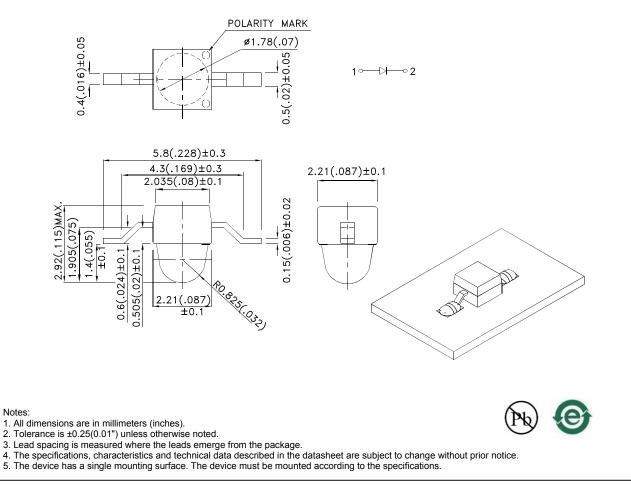
#### **Features**

- Subminiature package.
- Z-Bend lead.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- · RoHS compliant.

#### Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

#### **Package Dimensions**



SPEC NO: DSAC0418 **APPROVED: WYNEC** 

REV NO: V.6 **CHECKED: Allen Liu**  DATE: APR/14/2011 DRAWN: J.Yu

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#### Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM27CGCK09	Green (AlGaInP)	Water Clear	400	600	20°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	570		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	I⊧=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.1	2.5	V	I⊧=20mA
lr	Reverse Current	Green		10	uA	Vr=5V

Notes:

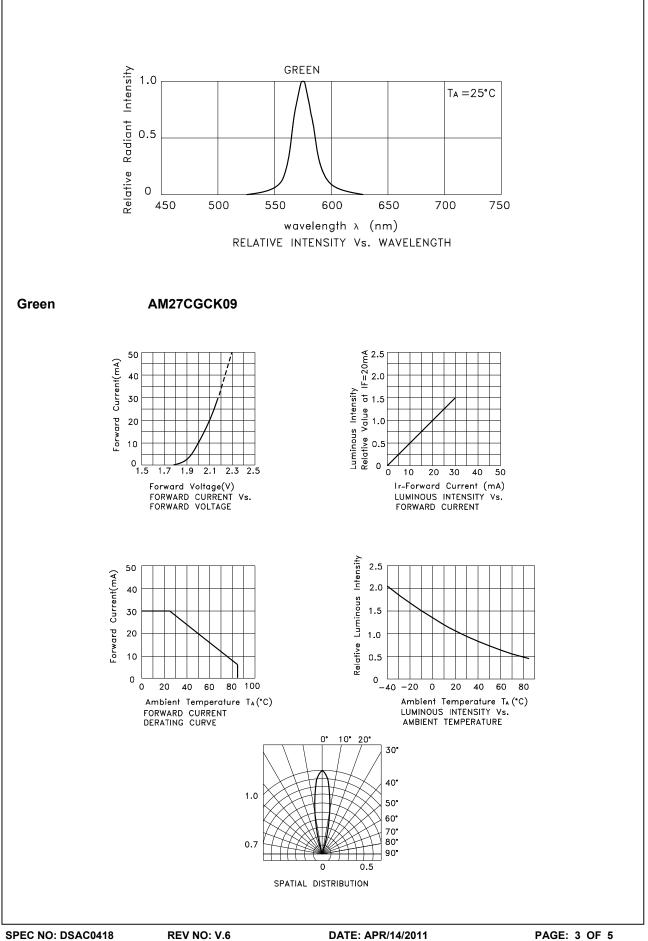
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

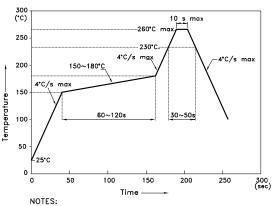
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



### AM27CGCK09

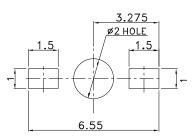
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

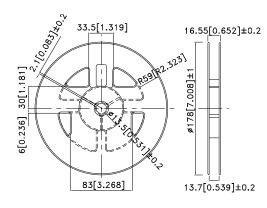


NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

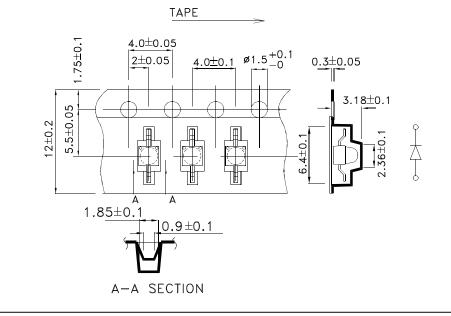
**Recommended Soldering Pattern** (Units : mm; Tolerance: ± 0.1)







**Tape Dimensions** (Units : mm)



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